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Docket No.: KAW-318-USAP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant: Takashi ITO et al.

Art Unit: 3729

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Examiner: TO BE ASSIGNED

Docket No: KAW-318-USAP

Customer No: 28892

For: Optical Device Molding Die Designing Method

PTO FORM 1449 SUBMISSION

FOREIGN PATENT DOCUMENTS				
Examiner Initials*	Foreign Patent Document Number	Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	T**
/M.P./	JP 2002-96344 English Abstract	Sony Corporation	April 2, 2002	

Examiner Signature	/Michael Piery/	Date Considered	10/25/2007
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\*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

\*\*Applicant is to place a check mark here if English language translation is attached